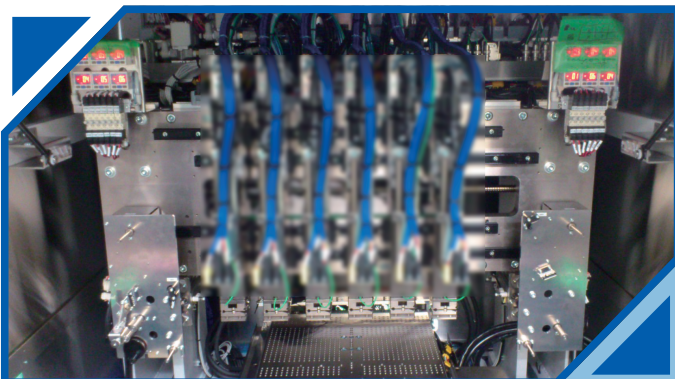


Multi Head TCB Equipment

HTB-300W

FOSB/FOUP
2.xD/3D, Chiplet, Hybrid Bonding



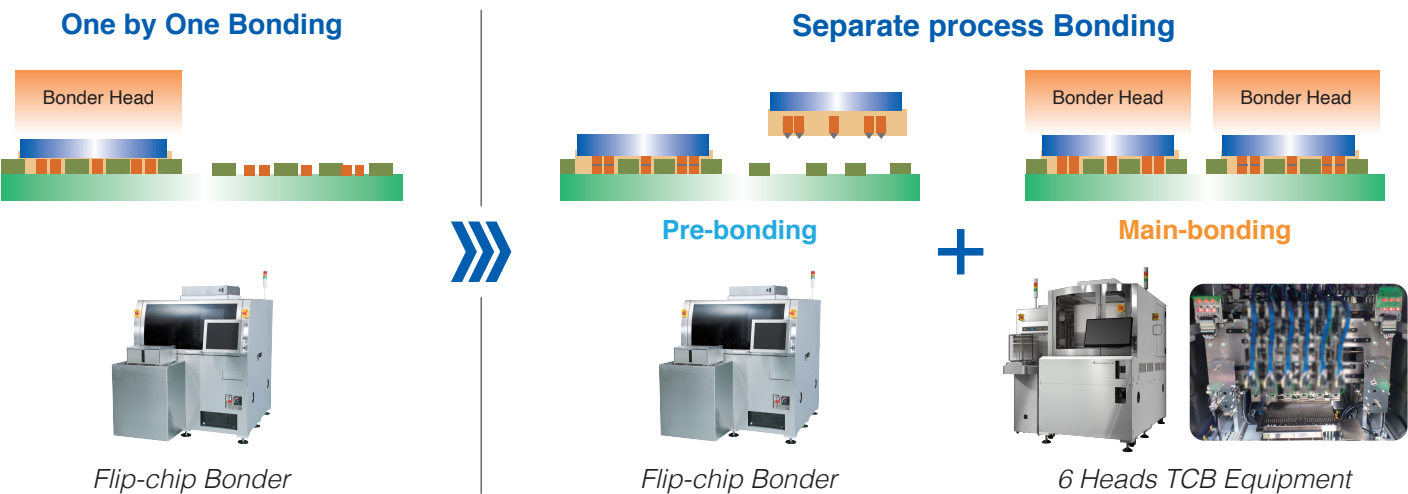
This is a 6-head equipment that improves throughput, which is the biggest issue in Thermal Compression Bonding.

Specifications

Items		Contents
Applicable Subst Size		$\phi 300\text{mm}$ Wafer $t=0.4\text{mm}\sim 1.0\text{mm}$ The 12-inch magazine is FOSB/FOUP compatible.
Target part size		$\square 0.5\text{mm}\sim \square 28\text{mm}$ $t=0.1\text{mm}\sim 1.0\text{mm}$
Mountable area		Same as substrate size
Dimension & Weight		Width: 1700mm xDepth: 1850mm xHeight: 1800mm(excl.signal tower) Weight: Approx 2000kg(Including wafer transfer)
power source	Power Supply	3-phases AC 200V $\pm 5\%$ 30A(50/60Hz) Single-phase AC 200V $\pm 5\%$ 210A(6Head \times 30A, stage30A) 3-phases AC 200V $\pm 5\%$ 15A(50/60Hz)···wafer transfer
	Dry Air	0.5MPa($\pm 10\%$) 1000 L/min(A.N.R)
	Vacuum	-80 kPa($\pm 10\%$)
Bonding Time		Depends on the process
Head Pressing		10N \sim 500N $\pm 5\%$ (need consultation)
Head Heating		RT \sim 450°C $\pm 5^\circ\text{C}$ (Pulse heat)※Temp of heater surface
Stage Heating		RT \sim 200°C $\pm 10^\circ\text{C}$ (Constant heat)※Temp of stage surface
Operation		LCD touch panel

Proposal of implementation

Temporary bonding is performed with a flip chip bonder instead of local reflow, which was performed for each chip with a flip chip bonder, and then final bonding is performed with the 6head of HTB-300. Contributes to improved productivity.



Contact us

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●Specifications and appearance contained herein are subject to change without prior notice.

●The contents of this catalog are as of April 2023